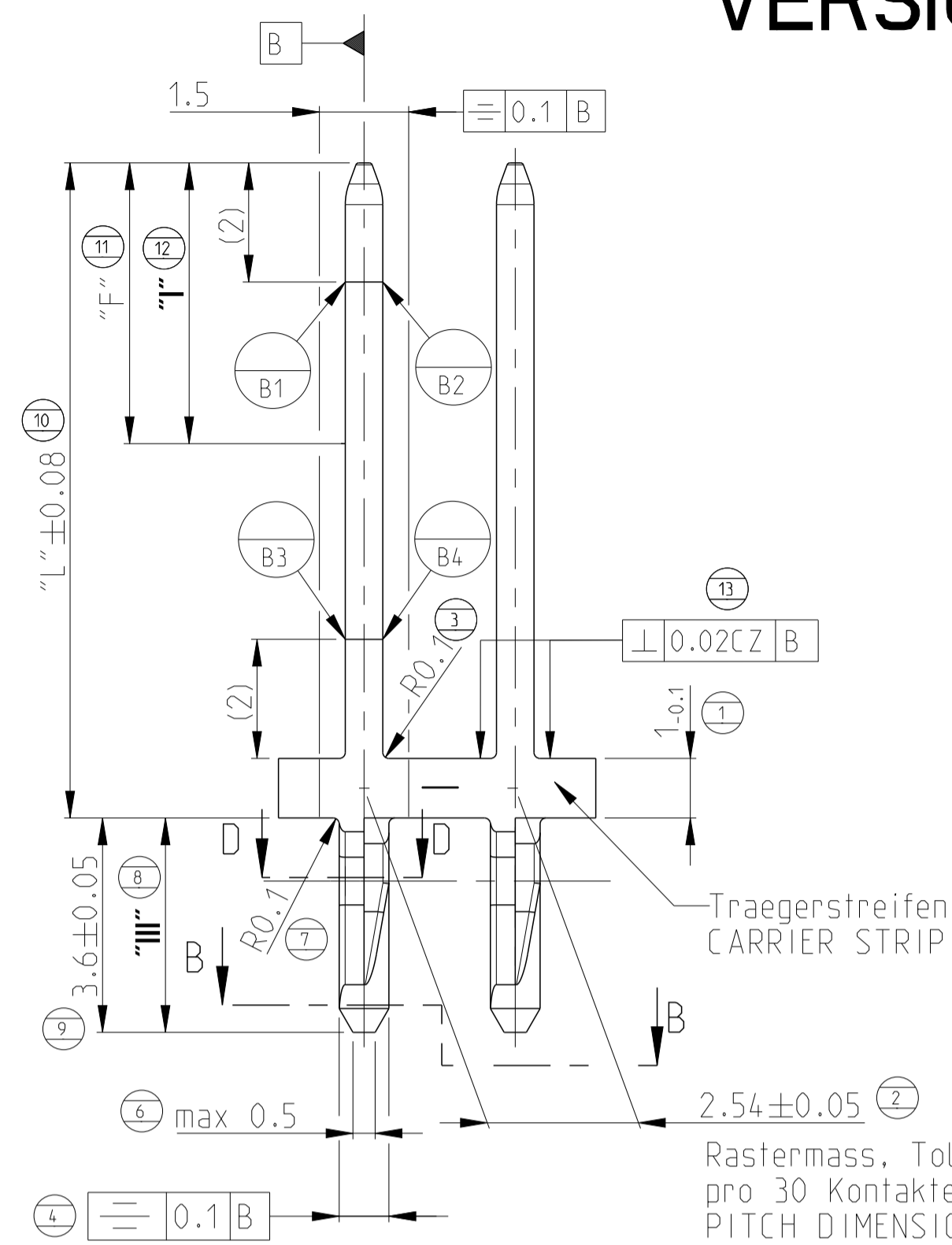
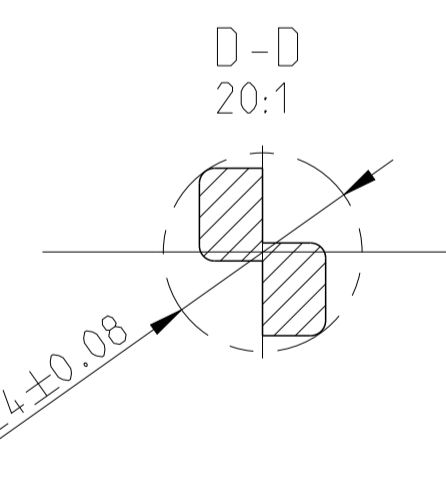
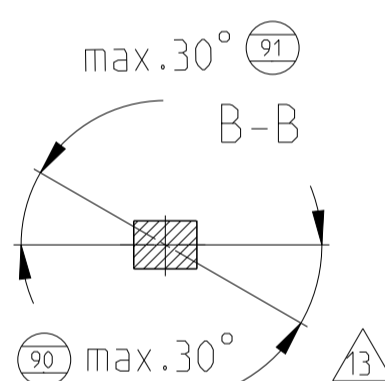


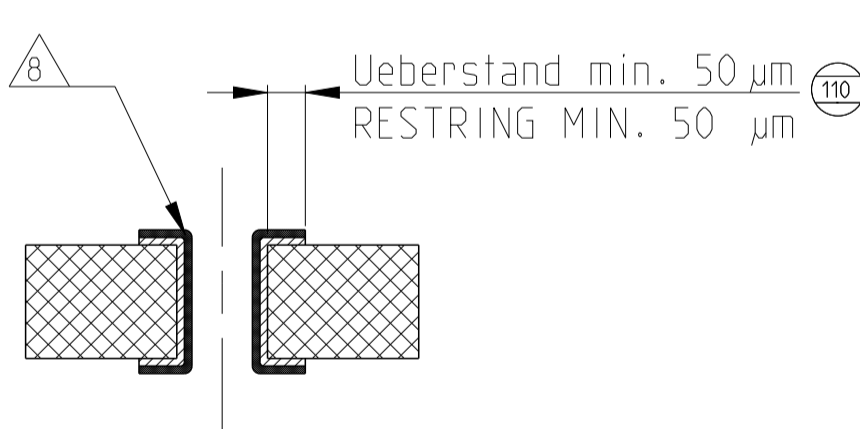
# VERSION A



Rastermass, Toleranz pro 30 Kontakte ±0.2  
PITCH DIMENSION.TOLERANCES PER 30 CONTACTS ±0.2



## Lochaufbau in der Leiterplatte HOLE CONSTRUCT FOR PCB



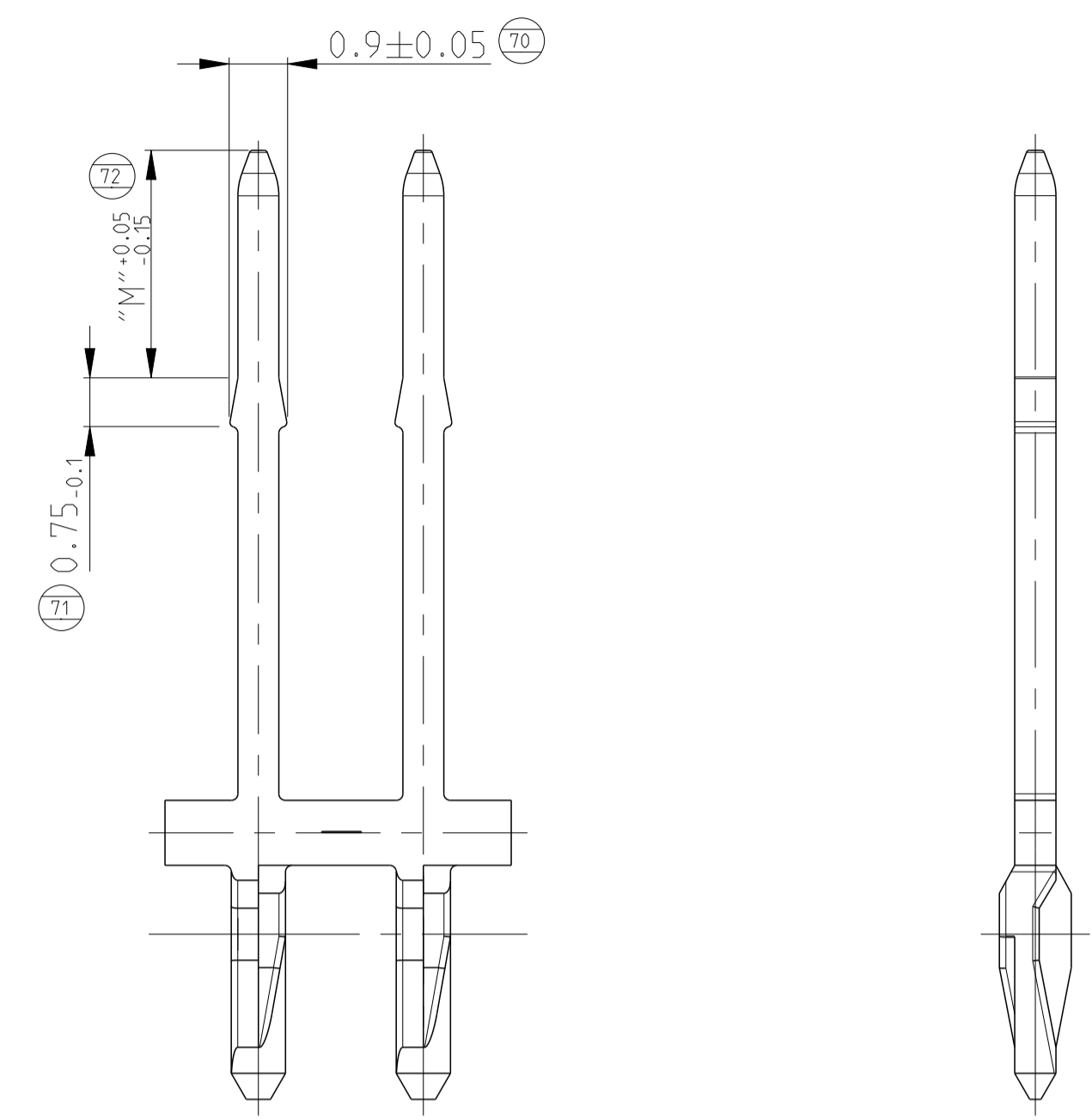
Lochaufbau LP HOLE CONSTRUCT PCB	△10	△11	△12
Kupferschicht COPPER COATING	25-75 µm	25-75 µm	25-50 µm
Zinn/Blei Schicht TIN/LEAD COATING	4-10 µm	-	-
Zinn Schicht TIN COATING	-	-	0.5-1.5 µm
Nickel Schicht NICKEL COATING	-	max. 5 µm	-
Gold Schicht GOLD COATING	-	max. 0.2 µm	-
Bohr Ø HOLE DIA.	1.15±0.025	1.15±0.025	1.15±0.025
Plattierter Ø PLATED DIA.	1 +0.09 -0.06	1 +0.09 -0.06	1.07+0.055 -0.045

<b>Zone "I" AREA</b>	Goldaufuehrung: 0.8 µm bis 2 µm Au ueber Ni GOLD VERSION: 0.8 µm TO 2 µm Au OVER Ni Zinn-Ausfuehrung: 1 µm bis 3 µm Sn TIN-VERSION: 1 µm TO 3 µm Sn SILVER-VERSION 1.5 µm to 5 µm Ag over Ni
<b>Zone "II" AREA</b>	Schichtdicke: 1.3 µm bis 2.2 µm Ni COAT THICKNESS: 1.3 µm TO 2.2 µm Ni FOR PN 8-963964-8 regarding note △1
<b>Zone "III" AREA</b>	Schichtdicke: 0.8 µm bis 1.8 µm Sn ueber Ni COAT THICKNESS: 0.8 µm TO 1.8 µm Sn OVER Ni

△1 THE PN 8-963964-8 is in development status  
The 8-963964-8 is not released for serial production  
PN 8-963964-8 ist in dem Entwicklungsstand.  
Part number 8-963964-8 ist nicht freigegeben für serienproduktion

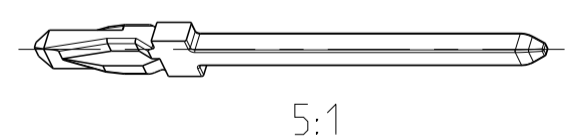
# VERSION B

FOR MISSING DIMENSIONS SEE VERSION A



- 1 Massgebend ist der deutsche Text  
ONLY THE GERMAN LANGUAGE VERSION SHALL BE BINDING
- △ Verwendung fuer Leiterplattendicke: 1.6 ± 0.14mm  
USED ON PCB THICKNESS: 1.6 ± 0.14mm
- 3 :
- 4 Lötbarkeit nach DIN 40046  
SOLDERABILITY ACCORDING TO DIN 40046
- △ Kontaktstift siehe Zeichnung, TE 114-94201 Version B  
CONTACT PIN SEE DRAWING TE 114-94201 VERSION B
- △ Zustand vor dem Einpressen  
STATUS BEFORE INSERTION
- 7 Zulaessige Saebelfoermigkeit: 40mm/m  
PERMITTED "SABERSHARPNESS": 40mm/m
- △ Einpresszone fuer 1.6mm Leiterplatte  
Anforderung an Leiterplattenloch, siehe Tabelle 1  
PRESS-IN AREA FOR 1.6mm PCB  
REQUIREMENTS ON PCB HOLE. SEE TABLE 1

- △ Verpackungseinheit: 50.000 Stck. auf Einweg Kunststoff-Spule Ø 588mm  
mit Zwischenlagenpapier, 3 Spulen im Karton  
PACKAGING UNIT: 50.000 PCS ON ONE-WAY PLASTIC REEL DIA.588MM  
WITH INTERLEAVING PAPER, 3 REELS IN BOX.
- △ Lochaufbau (Zinn/Blei) in der Leiterplatte (siehe Tabelle 1)  
HOLE CONSTRUCT (TIN/LEAD) FOR PCB (SEE TABLE 1)
- △ Lochaufbau (Nickel/Gold) in der Leiterplatte (siehe Tabelle 1)  
HOLE CONSTRUCT (NICKEL/GOLD) FOR PCB (SEE TABLE 1)
- △ Lochaufbau (Zinn) in der Leiterplatte (siehe Tabelle 1)  
HOLE CONSTRUCT (TIN) FOR PCB (SEE TABLE 1)
- △ Verdrehung Action Pin Spitze max. 30 °  
DISTORTION OF ACTION PIN TIP MAX. 30 DEG.
- △ Material spezifiziert nach UNS C19002  
MATERIAL SPECIFIED ACCORDING TO UNS C19002
- △ Spulen mit Kunststoff-Spule PN 1-1498100-8 mit Zwischenlagenpapier  
PN 1-740973-2, Transportkarton 973051-2  
REELLED ONTO PLASTIC REEL PN 1-1498100-8 WITH INTERLEAVING  
PAPER PN 1-740973-2, SHIPPING CARTON 973051-2
- △ Spulen mit Spule PN 725654-9 mit Zwischenlagenpapier PN 704973-3.  
Transportkarton 973051-2  
REELLED ONTO REEL PN 725654-9 WITH INTERLEAVING PAPER PN 704973-3, SHIPPINGCARTON 973051-2
- △ 1.3 µm bis 2.5 µm Nickel nach Formgebung ueber alles  
1.3 µm TO 2.5 µm NICKEL UPON PLATING AFTER FORMING SEQUENCE



VERSION	TE CONNECTIVITY BESTELL-NR. ORDER NO.	REV.	MATERIAL	OBERFLAECHE SURFACE AREA "F"	PCB-HOLE SPEC. LP-Bohrung Spez.	GRAMM GEWICHT WEIGHT	"F"	"L"	"M"	"N"				
A	7-963964-9	A	CuNiSi R580S	Zinn/TIN	0.05	7	21.3	-	24.9					
	6-963964-5	A		Zinn/TIN							7	11.4	-	15
	8-963964-7	A		Zinn/TIN							7	11.1	-	14.7
	2-963964-8	A		Zinn/TIN							7	9.2	-	12.8
	8-963964-8	A		Silver/Silber							7	11.1	-	14.7
3-963964-7	A	Gold/GOLD		5.5							11.1	-	14.7	
B	2-963964-7	A		Zinn/TIN							7	11.1	-	14.7
	2-963964-6	B		Zinn/TIN							7	13.6	7.75	17.2
	2-963964-5	C		Zinn/TIN							8.2	17.8	9.25	21.4
	9-963964-4	A		Zinn/TIN							7	13.6	7.75	17.2
	8-963964-4	B		Zinn/TIN							7	9.8	-	13.4
A	3-963964-4	A		Gold/GOLD							5.5	9.8	-	13.4
	2-963964-4	B		Zinn/TIN							7	9.8	-	13.4
	1-963964-4	B		Gold/GOLD							5.5	9.8	-	13.4
	2-963964-3	B		Zinn/TIN							7	8.05	-	11.65
	1-963964-3	B	Gold/GOLD	5.5	8.05	-	11.65							

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER GPS (ISO STANDARDS)

OWN: C. Beu 02DEC2002  
CHK: T. Sieler 10DEC2002

TE Connectivity

NAME: MGS ACTION PIN FOR 1mm HOLE ACTION PIN fuer 1mm Loch, freistehend

SIZE: A1 CAGE CODE: 00779 DRAWING NO: 963964

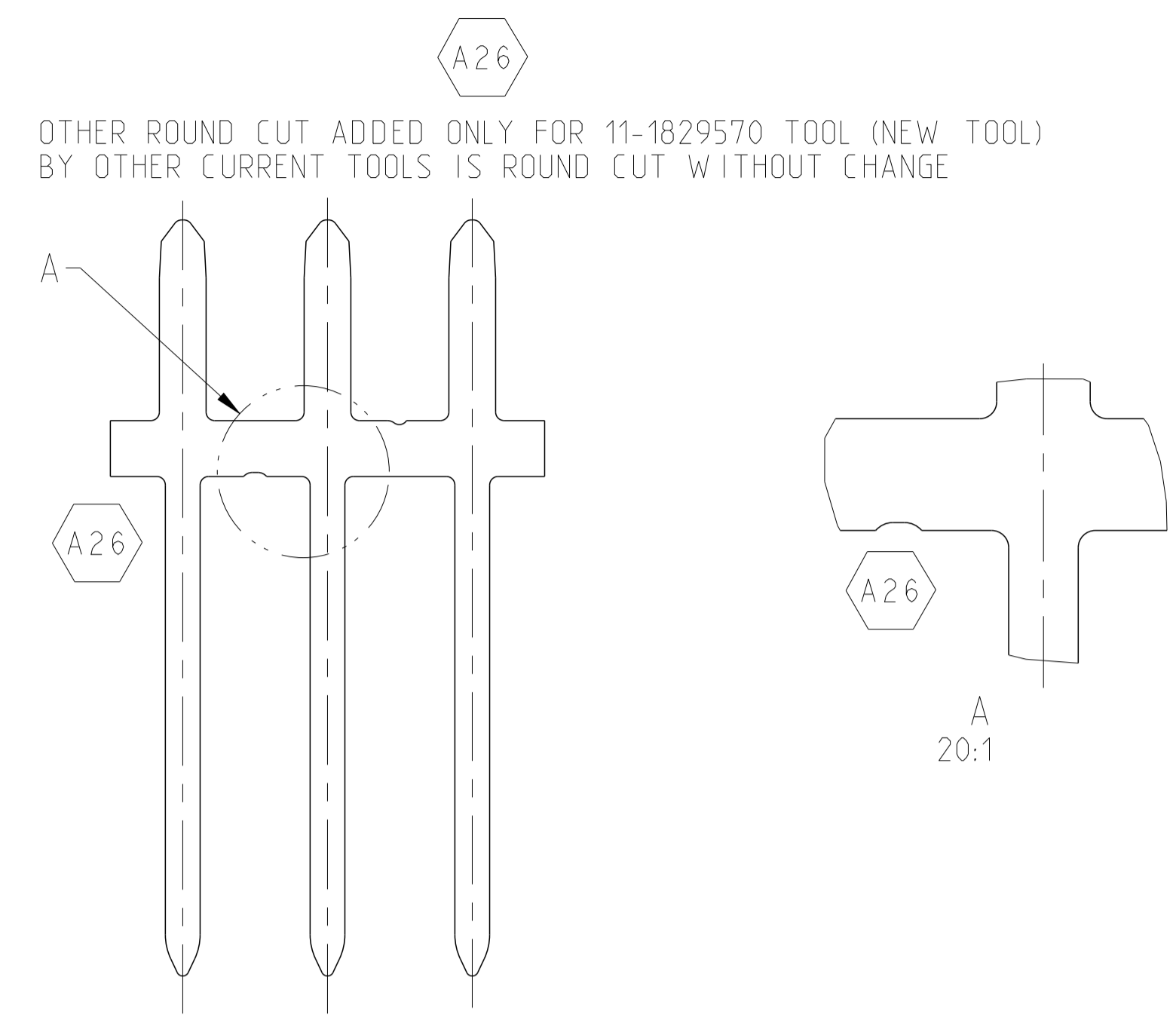
MATERIAL: CuNiSi R580S

WEIGHT: -

CUSTOMER DRAWING

SCALE: 5:1 SHEET: 1 OF 2

LOC	DIST	REV	DATE	BY	APPV
GT	-				



THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN C. Beu CHK T. Sieler	02DEC2002 10DEC2002		
DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED:			
		0 PLC ±0.5	1 PLC ±0.2	NAME MQS	
		2 PLC ±0.1	3 PLC ±	PRODUCT SPEC 108-18643	
		4 PLC ±	ANGLES ±2°	APPLICATION SPEC	
MATERIAL CuNiSi R5B0S		FINISH		SIZE A1	
				CAGE CODE 00779	
				DRAWING NO 963964	
				RESTRICTED TO	
				SCALE 10:1	
				SHEET 2 OF 2	
				REV A26	